Center for Nanoscale Science and Technology
Nanoscale User Facility

Usage Fee Schedule

Effective March 1, 2008

	Hourly Rate	Hourly Rate w/ Waiver
Base Nanofab Use	$54.00	$27.00
Includes Wet Chemistry, Contact Lithography, Metrology Equipment (Ellipsometer, Reflectometer, Profilometer, Optical Microscope, 4-Point Probe)		
Specific Tools		
Deep Silicon Etcher	207.00	69.00
Chlorine Metal Etcher	181.00	53.00
Oxford Etcher (1 and 2)	181.00	53.00
Fluorine-based RIE (Si, Si02, SiNx)	152.00	53.00
Fluorine-based RIE (metals)	152.00	53.00
XeF2 Etcher	158.00	53.00
Plasma Asher	85.00	27.00
Critical Point Dryer	105.00	48.00
Rapid Thermal Processor	190.00	64.00
Thermal Evaporators (Denton, CVC, Myers)	117.00	37.00
Electron Gun Evaporator	139.00	48.00
Sputterer (1 and 2)	107.00	37.00
Parylene Deposition	128.00	40.00
PECVD	159.00	53.00
Atmospheric Furnaces (oxidation, doping, annealing)	90.00	32.00
Low pressure CVD Furnaces (SiN, Poly-Si, LTO)	154.00	53.00
Nano-imprint Lithography	115.00	37.00
Wafer Bonder	160.00	64.00
Mask Writer	142.00	57.00
Dicing Saw	117.00	37.00
FESEM	160.00	53.00
FIB	381.00	106.00
JEOL-6400 E-Beam Lithography	206.00	64.00
Vistec/Leica VB-300-UHR E-beam Lithography	1,228.00	373.00
AFM (1 and 2)	137.00	55.00
Wire Bonder	124.00	49.00
Optical Scopes	111.00	46.00
Processing Services		
Staff Time (does not include Base Nanofab Use or Specific Tool fees)	116.00	116.00